

### STG5223

# Low voltage 0.5 Ω dual SPDT switch with break-before-make

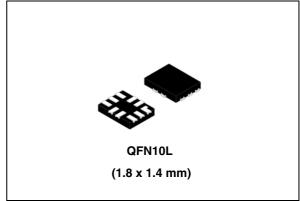
#### **Features**

- Ultra low power dissipation:  $I_{CC} = 0.2 \mu A \text{ (max.)}$  at  $T_A = 85 \text{ °C}$
- Low ON resistance:
  - $R_{ON}$  = 0.50  $\Omega$  (max.  $T_A$  = 25 °C) at  $V_{CC}$  = 4.3 V
  - R<sub>ON</sub> = 0.55  $\Omega$  (max. T<sub>A</sub> = 25 °C) at V<sub>CC</sub> = 3.6 V
  - $R_{ON}$  = 0.55  $\Omega$  (max.  $T_A$  = 25 °C) at  $V_{CC}$  = 3.0 V
- Wide operating voltage range: V<sub>CC</sub> (opr) = 1.65 V to 4.3 V single supply
- 5 V tolerant and 1.8 V compatible threshold on digital control input at V<sub>CC</sub> = 1.65 to 4.3 V
- Latch-up performance exceeds 300 mA (JESD 17)
- ESD performance: HBM > 2 kV (MIL STD 883 method 3015)

### **Description**

The STG5223 is a high-speed CMOS dual analog SPDT (single pole dual throw) switch or dual 2:1 multiplexer/demultiplexer bus switch fabricated in silicon gate C<sup>2</sup>MOS technology. It is designed to operate from 1.65 to 4.3 V, making this device ideal for portable applications.

It offers very low ON resistance (<0.5  $\Omega$ ) at V<sub>CC</sub> = 3.0 V. The nIN inputs are provided to control the switches. The switches nS1 are ON (connected to common ports Dn) when the nIN input is held high and OFF (high impedance state



exists between the two ports) when nIN is held low. The switches nS2 are ON (connected to common ports Dn) when the nIN input is held low and OFF (high impedance state exists between the two ports) when IN is held high. Additional key features are fast switching speed, break-beforemake delay time and ultra low power consumption. All inputs and outputs are equipped with protection circuits against static discharge, giving them ESD immunity and transient excess voltage immunity.

Table 1. Device summary

Order code	Package	Packaging
STG5223QTR	QFN10L (1.8 x 1.4 mm)	Tape and reel

Contents STG5223

# **Contents**

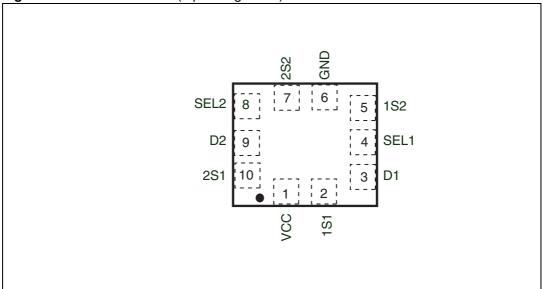
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STG5223 Pin settings

# 1 Pin settings

### 1.1 Pin connection

Figure 1. Pin connection (top through view)



# 1.2 Pin description

Table 2. Pin description

Pin number	Symbol	Name and function
1	V <sub>CC</sub>	Positive supply voltage
2	1S1	Independent channel
3	D1	Common channel
4	SEL1	Control
5	1S2	Independent channel
GND	GND	Ground (0V)
7	2S2	Independent channel
8	SEL2	Control
9	D2	Common channel
10	2S1	Independent channel

Warning: Exposed pad must be soldered to a floating plane. Do NOT connect to power or ground.

# 2 Input equivalent circuit and truth table

Figure 2. Input equivalent circuit

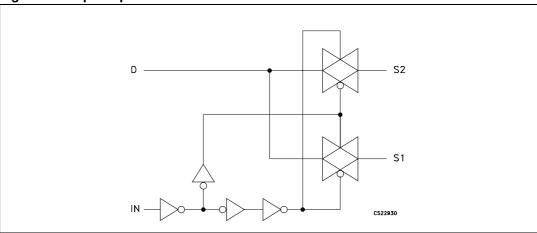


Table 3. Truth table

IN	Switch S1	Switch S2
Н	ON	OFF <sup>(1)</sup>
L	OFF <sup>(1)</sup>	ON

1. High impedance

STG5223 Maximum rating

## 3 Maximum rating

Stressing the device above the rating listed in the "Absolute maximum ratings" table may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those indicated in the operating sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Refer also to the STMicroelectronics SURE Program and other relevant quality documents.

Table 4. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	Supply voltage	-0.5 to 5.5	V
VI	DC input voltage	-0.5 to V <sub>CC</sub> + 0.5	V
V <sub>IC</sub>	DC control input voltage	-0.5 to 5.5	V
V <sub>O</sub>	DC output voltage	-0.5 to V <sub>CC</sub> + 0.5	V
I <sub>IKC</sub>	DC input diode current on control pin (V <sub>SEL</sub> < 0 V)	-50	mA
I <sub>IK</sub>	DC input diode current (V <sub>IN</sub> < 0 V)	±50	mA
I <sub>OK</sub>	DC output diode current	±20	mA
Io	DC output current	±300	mA
I <sub>OP</sub>	DC output current peak (pulse at 1 ms, 10% duty cycle)	±500	mA
I <sub>CC</sub> or I <sub>GND</sub>	DC V <sub>CC</sub> or ground current	±100	mA
P <sub>D</sub>	Power dissipation at T <sub>A</sub> =70 °C <sup>(1)</sup>	1120	mW
T <sub>STG</sub>	Storage temperature	-65 to 150	°C
T <sub>L</sub>	Lead temperature (10 sec)	300	°C

<sup>1.</sup> Derate above 70 °C by 18.5 mW/ °C

Maximum rating STG5223

# 3.1 Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Value	Unit	
V <sub>CC</sub>	Supply voltage		1.65 to 4.3	V
V <sub>I</sub>	Input voltage		0 to V <sub>CC</sub>	V
V <sub>IC</sub>	Control input voltage		0 to 4.3	V
V <sub>O</sub>	Output voltage	0 to V <sub>CC</sub>	V	
T <sub>op</sub>	Operating temperature		-40 to 85	°C
dt/dv	Input rise and fall time control input	V <sub>CC</sub> = 1.65 V to 2.7 V	0 to 20	ns/V
di/dv	input rise and rail time control input	V <sub>CC</sub> = 3.0 V to 4.3 V	0 to 10	7 115/V

# 4 Electrical characteristics

Table 6. DC specifications

						Value			
Symbol	Parameter	V <sub>CC</sub> (V)	Test condition	T	= 25	°C	-40 to 85 °C		Unit
		(V)		Min	Тур	Max	Min	Max	
		1.65 –1.95		0.65			0.65		
				V <sub>CC</sub>			V <sub>CC</sub>		
V <sub>IH</sub>	High level input	2.3 –2.5		1.2			1.2		V
	voltage	2.7 –3.0		1.3			1.3		
		3.0 –3.6		1.4			1.4		
		4.3		1.5			1.5		
		1.65 –1.95				0.25		0.25	
	Low level input	2.3 –2.5				0.25		0.25	
$V_{IL}$	voltage	2.7 –3.0				0.25		0.25	V
		3.0 –3.6				0.30		0.30	
		4.3				0.40		0.40	
		4.3			0.45	0.50		0.55	Ω
	Switch ON	3.6	$V_S = 0 \text{ V to } V_{CC}$ $I_S = 100 \text{ mA}$		0.50	0.55		0.65	
R <sub>ON</sub>	resistance	3.0			0.50	0.55		0.65	
		2.3			0.60	0.70		0.80	
		1.8			0.90	1.0		1.1	
$\Delta R_{ON}$	ON resistance match between channels <sup>(1)</sup>	2.7	$V_S = 1.5 \text{ V}$ $I_S = 100 \text{ mA}$		0.1				Ω
		4.3			0.15	0.20		0.20	
		3.6			0.15	0.20		0.20	
D	ON resistance	3.0	V <sub>S</sub> = 1.5 V		0.15	0.20		0.20	
R <sub>FLAT</sub>	flatness (2)	2.7	I <sub>S</sub> = 100 mA		0.15	0.20		0.20	Ω
		2.3			0.20	0.25		0.25	
		1.65			0.35	0.45		0.45	
I <sub>OFF</sub>	OFF state leakage current (nSn), (Dn)	4.3	V <sub>S</sub> = 0.3 or 4 V			±20		±100	nA
I <sub>IN</sub>	Input leakage current	0 –4.3	V <sub>SEL</sub> = 0 to 4.3 V			±0.05		±1	μА
I <sub>CC</sub>	Quiescent supply current	1.65 –4.3	V <sub>SEL</sub> = V <sub>CC</sub> or GND			±0.05		±0.2	μА

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Table 6. DC specifications (continued)

						Value			
Symbol	Parameter	V <sub>CC</sub> (V)	Test condition	TA	= 25	°C	-40 to	85 °C	Unit
		(-)		Min	Тур	Max	Min	Max	
	Quiescent		V <sub>1IN,</sub> V <sub>2IN</sub> = 1.65 V		±37	±50		±100	
I <sub>CCLV</sub>	supply current low voltage	4.3	V <sub>1IN</sub> , V <sub>2IN</sub> = 1.80 V		±33	±40		±50	μΑ
	driving		V <sub>1IN</sub> , V <sub>2IN</sub> = 2.60 V		±12	±20		±30	

<sup>1.</sup>  $\Delta R_{ON} = R_{ON(max)} - R_{ON(min)}$ 

**Table 7.** AC electrical characteristics ( $C_L$ = 35 pF,  $R_L$ = 50  $\Omega$ ,  $t_r$ =  $t_f \le 5$  ns)

			\			Value			
Symbol	Parameter	. V <sub>CC</sub> (V)	Test condition	T	A = 25	°C	-40 to	85 °C	Unit
		(-)		Min	Тур	Max	Min	Max	
		1.65 —1.95			0.30				
t <sub>PLH,</sub>	Propagation	2.3 —2.7			0.25				
t <sub>PHL</sub>	delay	3.0 -3.3			0.20				ns
		3.6 —4.3			0.20				
		1.65 —1.95	V <sub>S</sub> = 0.8 V		120				
+.	Turn-ON time	2.3 -2.7			65	85		90	
t <sub>ON</sub>	Turn-ON time	3.0 -3.3	V <sub>S</sub> = 1.5 V		42	55		65	ns
		3.6 -4.3			40	55		65	
		1.65 —1.95	V <sub>S</sub> = 0.8 V		45				
+	Turn-OFF time	2.3 —2.7			18	30		40	
t <sub>OFF</sub>	Turn-OFF time	3.0 -3.3	V <sub>S</sub> = 1.5 V		16	30		40	- ns
		3.6 —4.3			15	30		40	
		1.65 —1.95		2	17				
	Break-before-	2.3 —2.7	$C_L = 35 \text{ pF}$ $R_L = 50 \Omega$ $V_S = 1.5 \text{ V}$	2	10				
t <sub>D</sub>	make time delay	3.0 -3.3		2	8				ns
		3.6 -4.3		2	7				

<sup>2.</sup> Flatness is defined as the difference between the maximum and minimum value of on-resistance as measured over the specified analog signal ranges.

Table 7. AC electrical characteristics (continued) ( $C_L$ = 35 pF,  $R_L$ = 50  $\Omega$ ,  $t_r$ =  $t_f$   $\leq$ 5 ns)

		V <sub>cc</sub>		Value					
Symbol	Symbol Parameter		Test condition	T <sub>A</sub> = 25 °C		°C	-40 to 85 °C		Unit
		(V)		Min	Тур	Max	Min	Max	
		1.65 —1.95	C <sub>L</sub> =		43				
	Charge injection	2.3 —2.7	100 pF		51				20
Q Charge injection	3.0 -3.3	$R_L = 1 M\Omega$ $V_{GEN} = 0 V$		51				pC	
		3.6 —4.3	$R_{GEN} = 0 \Omega$		49				

Table 8.Analog switch characteristics ( $C_L = 5 \text{ pF}, R_L = 50 \ \Omega, T_A = 25 \ ^{\circ}\text{C}$ )

					_	Value			
Symbol	Parameter	V <sub>CC</sub> (V)	Test condition	T,	<sub>A</sub> = 25	°C	-40 to	85 °C	Unit
				Min	Тур	Max	Min	Max	
OIRR	Off isolation (1)		V <sub>S</sub> = 1 V <sub>RMS</sub> f = 100 kHz		-66				dB
Xtalk	Crosstalk	1.65 —4.3	V <sub>S</sub> = 1 V <sub>RMS</sub> f = 100 kHz		-72				dB
THD	Total harmonic distortion	2.3 —4.3	$R_L = 600 \Omega$ $V_{SEL} = 2 V_{PP}$ $f = 20 Hz to$ $20 kHz$		0.02				%
BW	-3dB bandwidth	1.65 —4.3	$R_L = 50 \Omega$		55				MHz
C <sub>IN</sub>	Control pin input capacitance				7				
C <sub>ON</sub>	Sn port capacitance when switch is enabled	3.3	f = 1 MHz		114				
C <sub>OFF</sub>	Sn port capacitance when switch is disabled	3.3	f = 1 MHz		40				pF
C <sub>D</sub>	D port capacitance when the switch is enabled	3.3	f = 1 MHz		114				

<sup>1.</sup> Off isolation = 20  $Log_{10}$  ( $V_D/V_S$ ),  $V_D$  = output.  $V_S$  = input at off switch

Test circuit STG5223

# 5 Test circuit

Figure 3. ON resistance

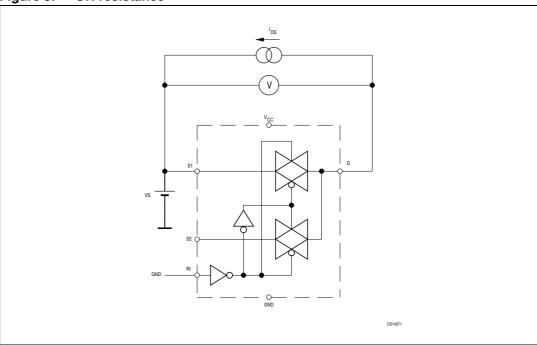
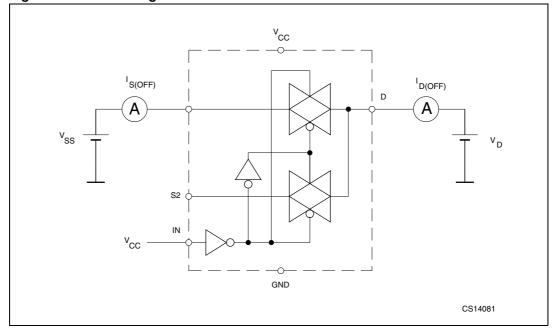


Figure 4. OFF leakage



STG5223 Test circuit

Figure 5. OFF isolation

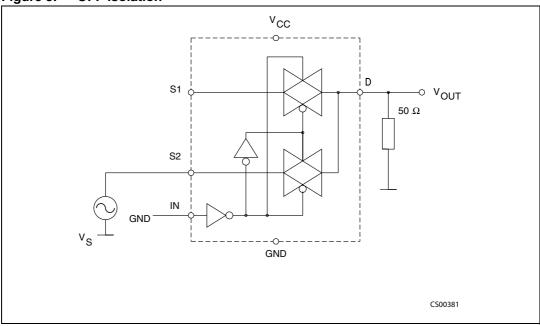
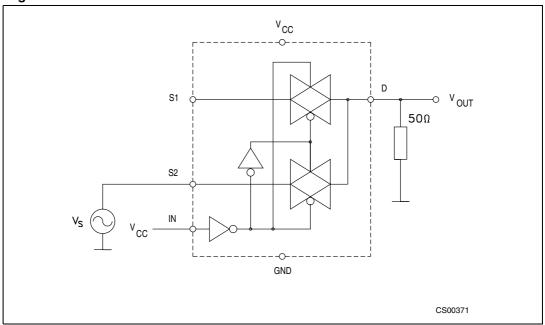


Figure 6. Bandwidth



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Figure 7. Channel-to-channel crosstalk

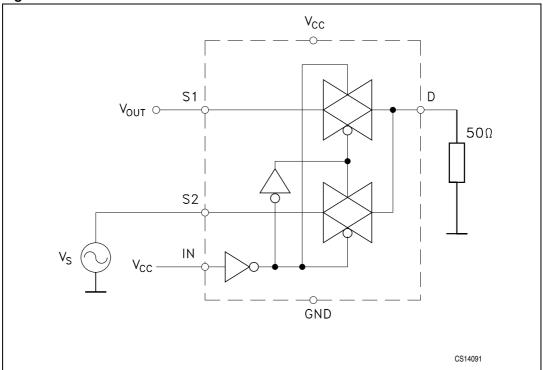
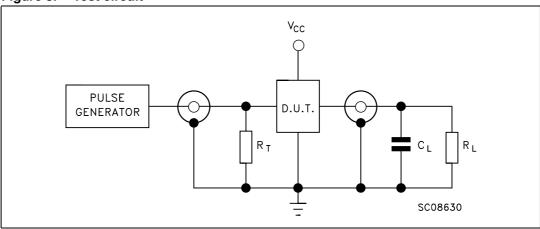


Figure 8. Test circuit



- 1.  $C_L = 5/35 \text{ pF}$  or equivalent (includes jig and probe capacitance)
- 2.  $R_L = 50 \Omega$  or equivalent
- 3.  $R_T = Z_{OUT}$  of pulse generator (typically 50  $\Omega$ )

STG5223 Test circuit

Figure 9. Break-before-make time delay

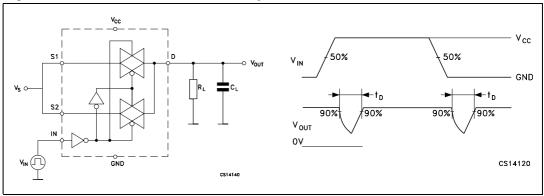


Figure 10. Charge injection (V<sub>GEN</sub> = 0, R<sub>GEN</sub> = 0  $\Omega$ , R<sub>L</sub> = 1 M $\Omega$ , C<sub>L</sub> = 100 pF)

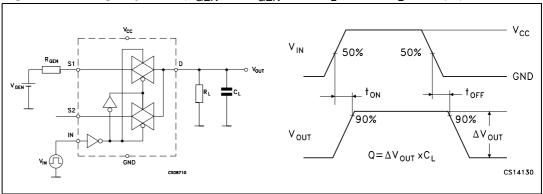
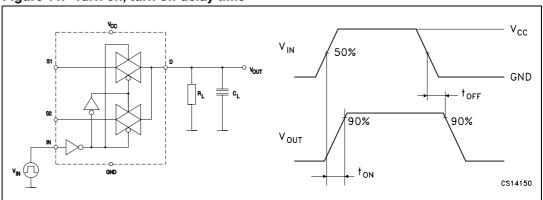


Figure 11. Turn on, turn off delay time



## 6 Package mechanical data

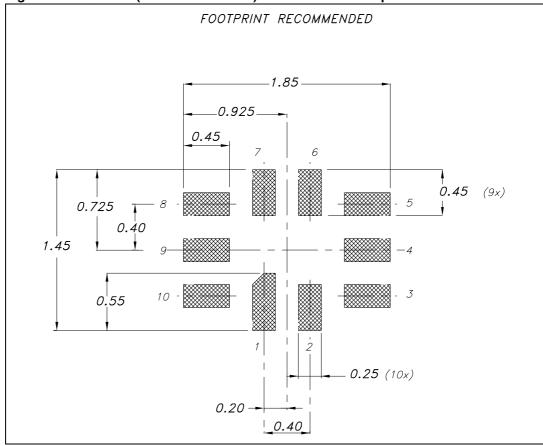
In order to meet environmental requirements, ST offers these devices in ECOPACK<sup>®</sup> packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

Figure 12. QFN10L (1.8 x 1.4 x 0.5 mm) package outline BOTTOM VIEW PIN 1 ID 8 (9x) **b** (10x) e/2-// 0.05 C -A3 SEATING PLANE A 1 C ○ 0.05 C 10x LEADS COPLANARITY 6 8 3 E/2 10 PIN 1 ID -D/2 TOP VIEW 7936048 D

Table 9. QFN10L (1.8 x 1.4 x 0.5 mm) mechanical data

Symbol		millimeters	
Symbol	Min	Тур	Max
Α	0.45	0.50	0.55
A1	0	0.02	0.05
A3		0.127	
b	0.15	0.20	0.25
D	1.75	1.80	1.85
E	1.35	1.40	1.45
е		0.40	
L	0.35	0.40	0.45
L1	0.45	0.50	0.55

Figure 13. QFN10L (1.8 x 1.4 x 0.5 mm) recommended footprint



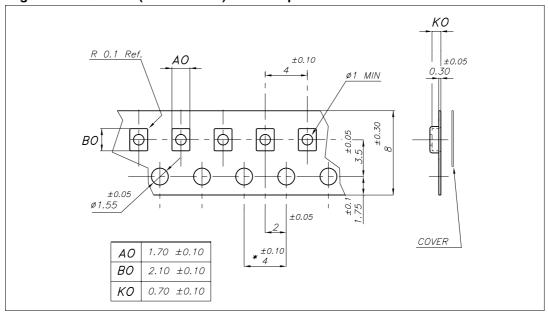
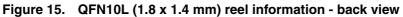
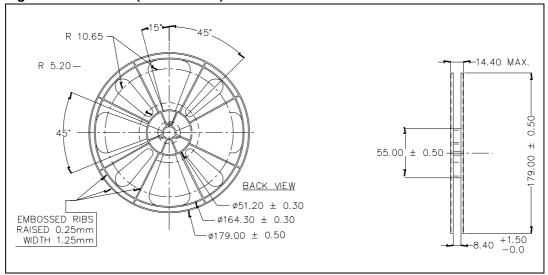


Figure 14. QFN10L (1.8 x 1.4 mm) carrier tape





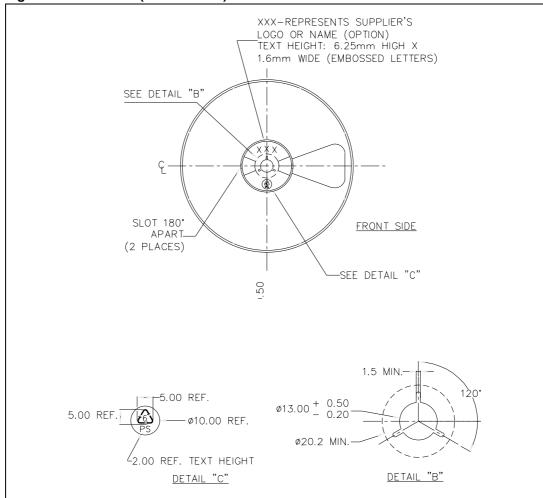


Figure 16. QFN10L (1.8 x 1.4 mm) reel information - front side

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Revision history STG5223

# 7 Revision history

Table 10. Document revision history

Date	Revision	Changes
10-Jan-2008	1	Initial release.

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